

L Number	Hits	Search T xt	DB	Time stamp
1	3	(yi-sang-hyun kim-young-nam).in.	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:01
2	75	multilayer with metalization	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:02
3	54	multi-layer with metalization	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:02
4	204	multiple with metalization	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:06
5	321	(multilayer with metalization) (multi-layer with metalization) (multiple with metalization)	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:02
6	15	((multilayer with metalization) (multi-layer with metalization) (multiple with metalization)) and crack?	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:02
7	14267	thermal adj stress	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:06
8	2659	crack? and (thermal adj stress)	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:04
12	3154	(257/750,758;438/622).CCLS.	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:06
13	3	multiple with metalization	EPO; JPO; DERWENT	2003/05/02 15:06
14	13917	thermal adj stress	EPO; JPO; DERWENT	2003/05/02 15:06
15	766	(thermal adj stress) and crack?	EPO; JPO; DERWENT	2003/05/02 15:06
16	187	((thermal adj stress) and crack?) and semiconductor	EPO; JPO; DERWENT	2003/05/02 15:08
10	225	(crack? and (thermal adj stress)) and 438/\$.ccls.	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:15
17	162	((crack? and (thermal adj stress)) and 438/\$.ccls.) and @ad<20010220	USPAT; US-PGPUB; IBM_TDB	2003/05/02 15:15